

DATA SHEET

TDA9820

Multistandard/dual channel TV FM
intercarrier sound demodulator

Product specification
Supersedes data of March 1991
File under Integrated Circuits, IC02

1996 Nov 20

Multistandard/dual channel TV FM intercarrier sound demodulator

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FEATURES

- Multistandard application for sound standards M, B/G, I and D/K
- Two alignment-free PLL FM demodulators
- Four-input source selector for one of the two FM demodulators
- Automatic second sound carrier mute
- Mono and dual channel application
- Low power consumption
- Few external components required.

GENERAL DESCRIPTION

The TDA9820 is a monolithic, integrated, multistandard TV FM intercarrier sound demodulator for all FM standards. The circuit contains two separate FM demodulators using Phase Locked Loop (PLL) reference frequency generation. The circuit requires a minimum number of external components.

QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_P	supply voltage (pin 14)		4.5	5.0	8.8	V
I_P	supply current (pin 14)		23	30	37	mA
I_M	AC peak current (pins 7 and 8)		–	–	1.5	mA
$V_{i(rms)}$	input signal (RMS value)	$\frac{S+N}{N} = 40$ dB	–	150	250	μ V
$V_{o(rms)}$	output signal (pins 7 and 8; RMS value)	$\Delta f_i = \pm 50$ kHz	0.4	0.5	0.6	V
$\frac{S+N}{N}$	signal plus noise-to-noise ratio (pins 7 and 8)	in accordance with "CCIR 468-3"	64	68	–	dB
$\alpha_{8/7}$	crosstalk attenuation	$f = 50$ to 12500 Hz	60	70	–	dB
RR	supply voltage ripple rejection (pins 7 and 8)	$V_{RR} < 200$ mV; $f = 70$ Hz	16	20	–	dB
T_{amb}	operating ambient temperature		0	–	70	$^{\circ}$ C

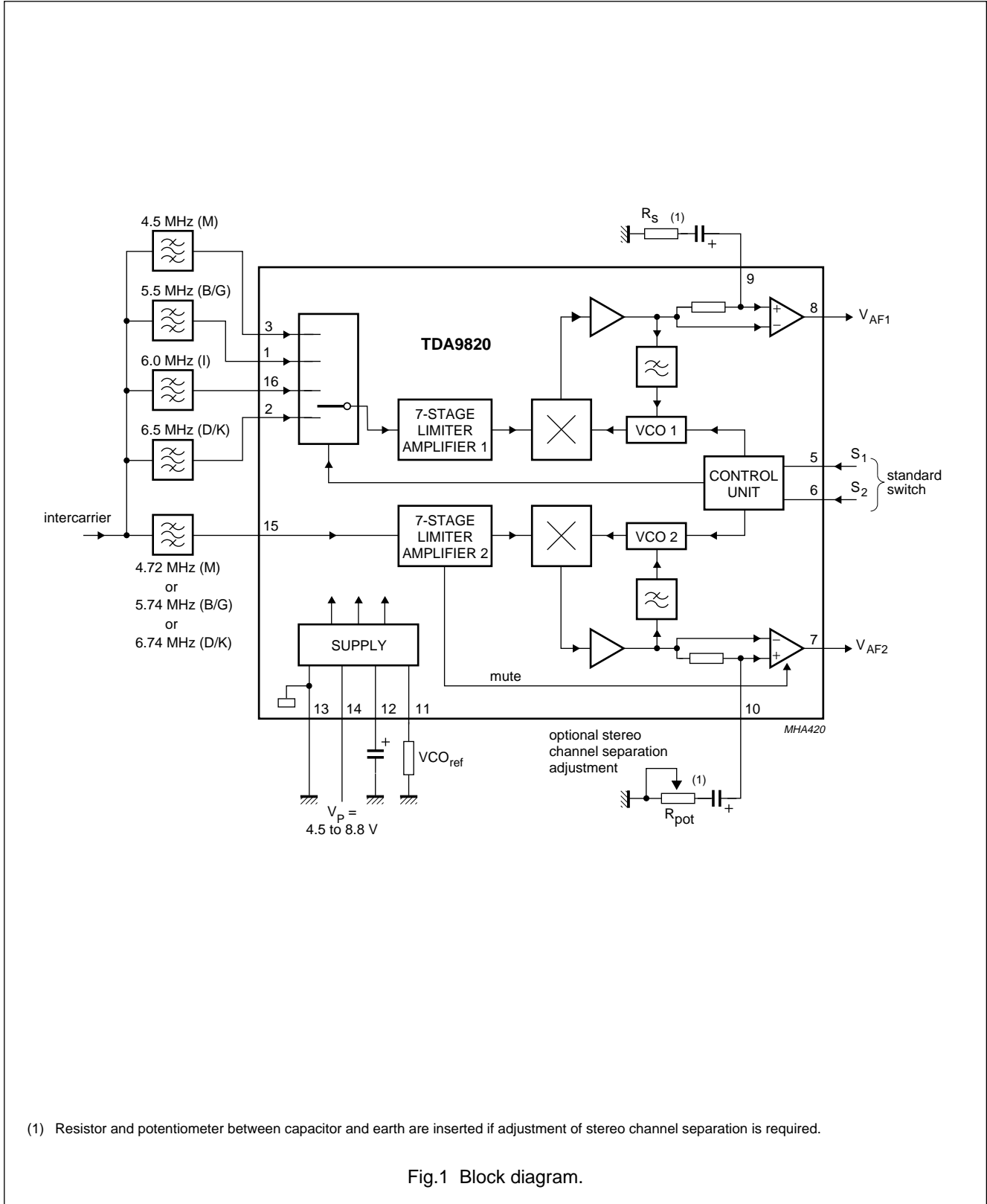
ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
TDA9820	DIP16	plastic dual in-line package; 16 leads (300 mil); long body	SOT38-1
TDA9820T	SO16	plastic small outline package; 16 leads; body width 7.5 mm	SOT162-1

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BLOCK DIAGRAM



(1) Resistor and potentiometer between capacitor and earth are inserted if adjustment of stereo channel separation is required.

Fig.1 Block diagram.

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PINNING

SYMBOL	PIN	DESCRIPTION
IN _{1(B/G)}	1	intercarrier input 1 at 5.5 MHz
IN _{1(D/K)}	2	intercarrier input 1 at 6.5 MHz
IN _{1(M)}	3	intercarrier input 1 at 4.5 MHz
n.c.	4	not connected
S ₁	5	standard switch bit 1 input
S ₂	6	standard switch bit 2 input
V _{AF2}	7	audio output voltage 2
V _{AF1}	8	audio output voltage 1
C ₁	9	decoupling capacitor 1
C ₂	10	decoupling capacitor 2
VCO _{ref}	11	VCO reference
C _{STAB}	12	supply voltage stabilization
GND	13	ground
V _P	14	supply voltage
IN ₂	15	intercarrier input 2
IN _{1(l)}	16	intercarrier input 1 at 6.0 MHz

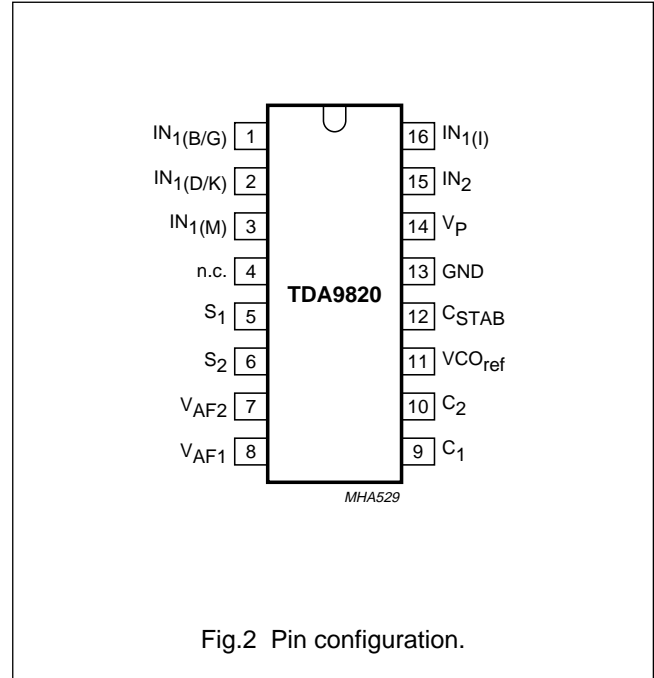


Fig.2 Pin configuration.

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FUNCTIONAL DESCRIPTION

The complete circuit consists of two separate channels, each consisting of a limiter-amplifier, FM demodulator and AF amplifier. Circuit operation is also described in Fig.1.

Source selector

The intercarrier signal is fed through external ceramic band-pass filters which are tuned to the sound carrier frequencies.

One of the four filtered sound carriers from pins 1, 2, 3 or 16 is fed to limiter-amplifier 1 via the appropriate electronic switch in the source selector. The electronic switch of the sound carrier is selected by the control unit (see Table 1).

The second sound carrier of the intercarrier signal is directly fed from pin 15 to limiter-amplifier 2.

FM demodulators

Each limiter-amplifier is AC-coupled into a FM demodulator. The integrated FM demodulator PLLs are alignment-free. The FM demodulator outputs are amplified to 500 mV (RMS value). High amplification and DC error signals of the PLLs, which are superimposed on the FM demodulator outputs, require DC decoupling at pins 9 and 10 of the AF amplifier inputs.

Stereo channel separation adjustment (optional)

Optimal stereo channel separation is achieved by adjusting V_{AF1} (pin 8) and V_{AF2} (pin 7) as follows:

1. V_{AF1} by a resistor in series with the DC decoupling capacitor at pin 9
2. V_{AF2} by a variable resistor in series with the DC decoupling capacitor on pin 10 to the same voltage as V_{AF1} .

Second sound carrier mute

The output of the second FM demodulator is muted when the signal level (signal and/or noise) at pin 15 is less than typically 0.5 mV (RMS value). This avoids an incorrect stereo or dual sound identification when a mono signal is transmitted. Therefore, with a mono transmission, there is no audio output at pin 7. When the signal level at pin 15 is greater than typically 1.0 mV (RMS value) mute is switched off.

Control unit

The control unit selects the required sound standard according to the voltages on pin 5 and pin 6. The control unit performs the following:

1. selects the free-running frequencies of VCO1 and VCO2
2. switches the source selector (the four possible combinations are shown in Table 1).

Table 1 Logic table; note 1

STANDARD	S1 (PIN 5)	S2 (PIN 6)	FREQUENCY VCO1 (MHz)	FREQUENCY VCO2 (MHz)	SOURCE SELECTOR CONNECTION
B/G	1	1	5.5	5.74	pin 1
M	1	0	4.5	4.72	pin 3
I	0	1	6.0	off	pin 16
D/K	0	0	6.5	6.74	pin 2

Note

1. In columns S1 and S2: 0 = LOW and 1 = HIGH.

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LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_P	supply voltage (pin 14)		-0.5	+9.0	V
V_i	input signal (pins 1, 2, 3, 15 and 16)		-0.5	+5.0	V
V_{sw}	switching voltage (pins 5 and 6)		-0.5	$V_P + 0.5$	V
t_s	short-circuit time (each pin except pins 13 and 14 to be tested; one at the time)		-	10	s
T_{stg}	storage temperature				
	device		-25	+125	°C
	device in packing		-25	+85	°C
T_j	junction temperature		-	150	°C
T_{amb}	operating ambient temperature		0	70	°C
V_{es}	electrostatic handling for all pins	note 1	-500	+500	V
		note 2	-4000	+4000	V

Notes

- Equivalent to discharging a 200 pF capacitor via a 0 Ω series resistor.
- Equivalent to discharging a 100 pF capacitor via a 1.5 k Ω series resistor.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	VALUE	UNIT
$R_{th\ j-a}$	thermal resistance from junction to ambient in free air		
	TDA9820 (DIP16)	74	K/W
	TDA9820T (SO16)	104	K/W

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CHARACTERISTICS

All voltages are measured to GND (pin 13); $V_P = 5\text{ V}$; $T_{\text{amb}} = 25\text{ }^\circ\text{C}$; $\Delta f_i = \pm 50\text{ kHz}$; $f_{\text{mod}} = 1\text{ kHz}$;
 $V_{1, 2, 3, 16/15} = 10\text{ mV}$ (RMS value); measurements taken in Fig.5; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Supply (pin 14)						
V_P	supply voltage		4.5	5.0	8.8	V
I_P	supply current		23	30	37	mA
Source selector and limiter-amplifier 1 (pins 1, 2, 3 and 16)						
V_I	DC input voltage	activated input	2.25	2.5	2.75	V
		not activated input	–	–	0.1	V
R_I	input resistance	activated input	480	600	720	Ω
		not activated input	–	–	600	Ω
$V_{i(\text{rms})}$	input signal (RMS value)	$\frac{S+N}{N} = 40\text{ dB}$	–	150	250	μV
	allowed input signal (RMS value)		200	–	–	mV
α_{ct}	crosstalk attenuation	not activated input to activated input	40	50	–	dB
Limiter-amplifier 2						
V_{15}	DC input voltage		2.25	2.5	2.75	V
$V_{15(\text{rms})}$	input signal (RMS value)	$\frac{S+N}{N} = 40\text{ dB}$; note 1	–	150	250	μV
	input signal for mute off (RMS value)		0.7	1.0	1.5	mV
	allowed input signal (RMS value)		200	–	–	mV
R_{15}	input resistance		480	600	720	Ω
δ	hysteresis of level detector		8	12	16	dB
PLL FM demodulators VCO1 and VCO2						
f_{VCO1}	free-running frequencies	$R_{11} = 27\text{ k}\Omega$; see Table 1	–	4.5	–	MHz
			–	5.5	–	MHz
			–	6.0	–	MHz
			–	6.5	–	MHz
f_{VCO2}	free-running frequencies	$R_{11} = 27\text{ k}\Omega$; see Table 1	–	4.7	–	MHz
			–	5.7	–	MHz
			–	6.7	–	MHz
Δf_{fr}	negative/positive free-running frequency spread		–	–	10	%
$D/\Delta f_{\text{fr}}$	drift of free-running frequencies	$T_{\text{amb}} = 0\text{ to }70\text{ }^\circ\text{C}$	–	500	750	kHz
$\Delta f_{\text{fr}(\text{shift})}$	shift of free-running frequencies	$4.5\text{ V} < V_P < 8.8\text{ V}$	–	200	300	kHz
$\Delta f_{\text{fr}(\text{ar})}$	negative/positive adjustment range of free-running frequencies	$R_{11} = 22\text{ k}\Omega$	1	–	–	MHz
R_{11}	adjustment resistance for free-running frequencies (pin 11)		15	–	29	k Ω

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S	negative slope of free-running frequency adjustment	$R_{11} = 22 \text{ k}\Omega$	–	200	–	kHz/k Ω
Δf_1	negative/positive catching range of PLLs		1.4	1.9	–	MHz
Δf_2	negative/positive holding range of PLLs		2.0	3.0	–	MHz
Output amplifiers AF1 (pin 8) and AF2 (pin 7)						
V_O	DC output voltage		1.8	2.1	2.5	V
$V_{o(\text{rms})}$	output signal (RMS value)		0.4	0.5	0.6	V
		clipping level	1.2	–	–	V
I_M	AC peak current		–	–	1.5	mA
I_O	DC source current		–	–	2.0	mA
$\Delta V_o/V_o$	absolute drift of AF output signals	$T_{\text{amb}} = 0 \text{ to } 70 \text{ }^\circ\text{C}$	–	0.7	–	dB
$\Delta V_{o1}/\Delta V_{o2}$	relative drift of AF output signals	$T_{\text{amb}} = 0 \text{ to } 70 \text{ }^\circ\text{C}$	–	0.2	–	dB
$\Delta V_{AF(1-2)}$	negative/positive difference between output signals	50 μs de-emphasis	–	0.3	1.0	dB
R_o	output resistance		–	100	150	Ω
$\alpha_{\text{cs(ar)}}$	adjustment range of channel separation	$R_s = 1.1 \text{ k}\Omega$; $R_{\text{pot}} = 2.2 \text{ k}\Omega$	1.5	–	–	dB
THD	total harmonic distortion	50 μs de-emphasis				
		pin 8	–	0.1	0.3	%
		pin 7	–	0.25	0.5	%
α_{AM}	AM suppression of AF(1-2)	50 μs de-emphasis; $m = 0.3$; $f_{\text{AM}} = 1 \text{ kHz}$	46	66	–	dB
$\frac{S + N}{N}$	signal plus noise-to-noise ratio	50 μs de-emphasis; in accordance with "CCIR 468-3"	64	68	–	dB
AF_{resp}	LOW-level AF frequency response	$\Delta V_{AF(1-2)} = -3 \text{ dB}$	–	–	20	Hz
	HIGH-level AF frequency response		200	–	–	kHz
$AM_{\text{res(rms)}}$	residual sound carrier signal and harmonics (RMS value)		–	50	80	mV
$\alpha_{8/7}$	crosstalk attenuation between AF outputs	$f = 50 \text{ to } 12500 \text{ Hz}$	60	70	–	dB
RR	supply voltage ripple rejection	$V_{\text{RR}} < 200 \text{ mV}$; $f_r = 20 \text{ Hz to } 200 \text{ kHz}$ $V_p = 5 \text{ V}$ $V_p = 8 \text{ V}$	16	20	–	dB
			24	28	–	dB
RR	supply voltage ripple rejection with improved application for $V_p = 5 \text{ V}$	$f_r = 20 \text{ Hz to } 3 \text{ kHz}$; see Fig.3 and note 2 $V_p = 4.5 \text{ V}$ $V_p = 4.75 \text{ V}$ $V_p = 5.0 \text{ V}$ $V_p = 5.5 \text{ V}$	18	24	–	dB
			21	27	–	dB
			24	30	–	dB
			21	27	–	dB

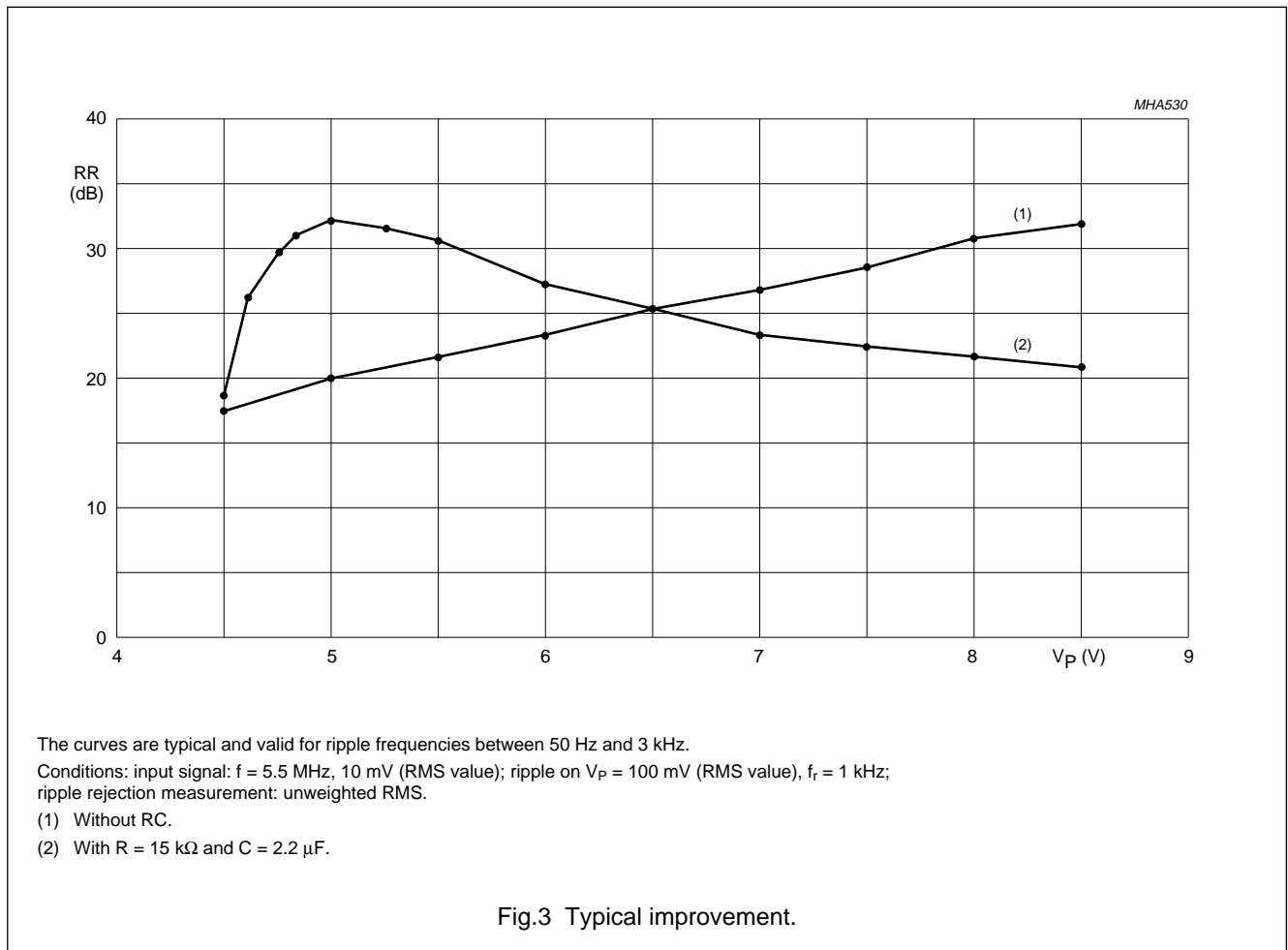
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SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Control unit; see Table 1						
$V_{5,6}$	voltage for LOW level		0	–	0.8	V
$I_{5,6}$	source current for LOW level	$0 < V_{5,6} < 0.8$	–	180	250	μA
$R_{5,6}$	allowed resistance to ground	$0 < V_{5,6} < 0.8$ (LOW-level)	–	–	3.0	$\text{k}\Omega$
V_5	voltage for HIGH level	note 3	2.2	–	V_P	V
V_6	voltage for HIGH level	note 3	1.8	–	V_P	V
$I_{5,6}$	sink current for HIGH level	$V_{5,6} = V_P$	–	–	10	μA

Notes

1. The output signal at pin 7 can only be measured when mute is disabled. This is achieved by inserting a resistor of 2.7 $\text{k}\Omega$ between pin 15 and ground. In this event the input impedance is 490 Ω .
2. Improvement of ripple rejection is possible by connecting series RC between pin 11 and pin 14 (15 $\text{k}\Omega + 2.2 \mu\text{F}$; see Fig.5) for a supply voltage of 4.5 to 5.5 V. The rejection of ripple frequencies up to 3 kHz is improved, but up to 200 kHz is worse; see Fig.3.
3. An open pin (n.c.) is interpreted as HIGH.



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INTERNAL CIRCUITRY

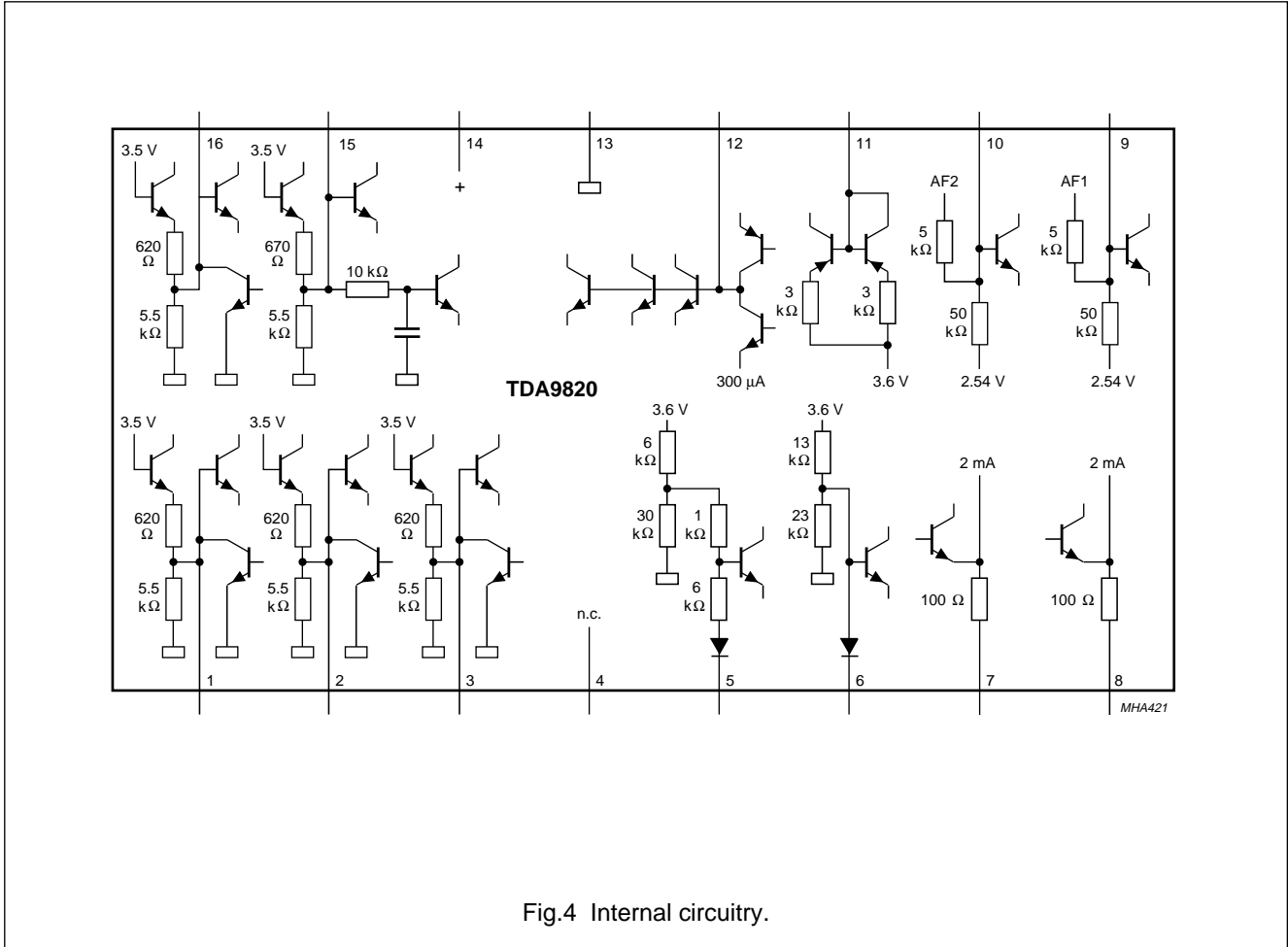
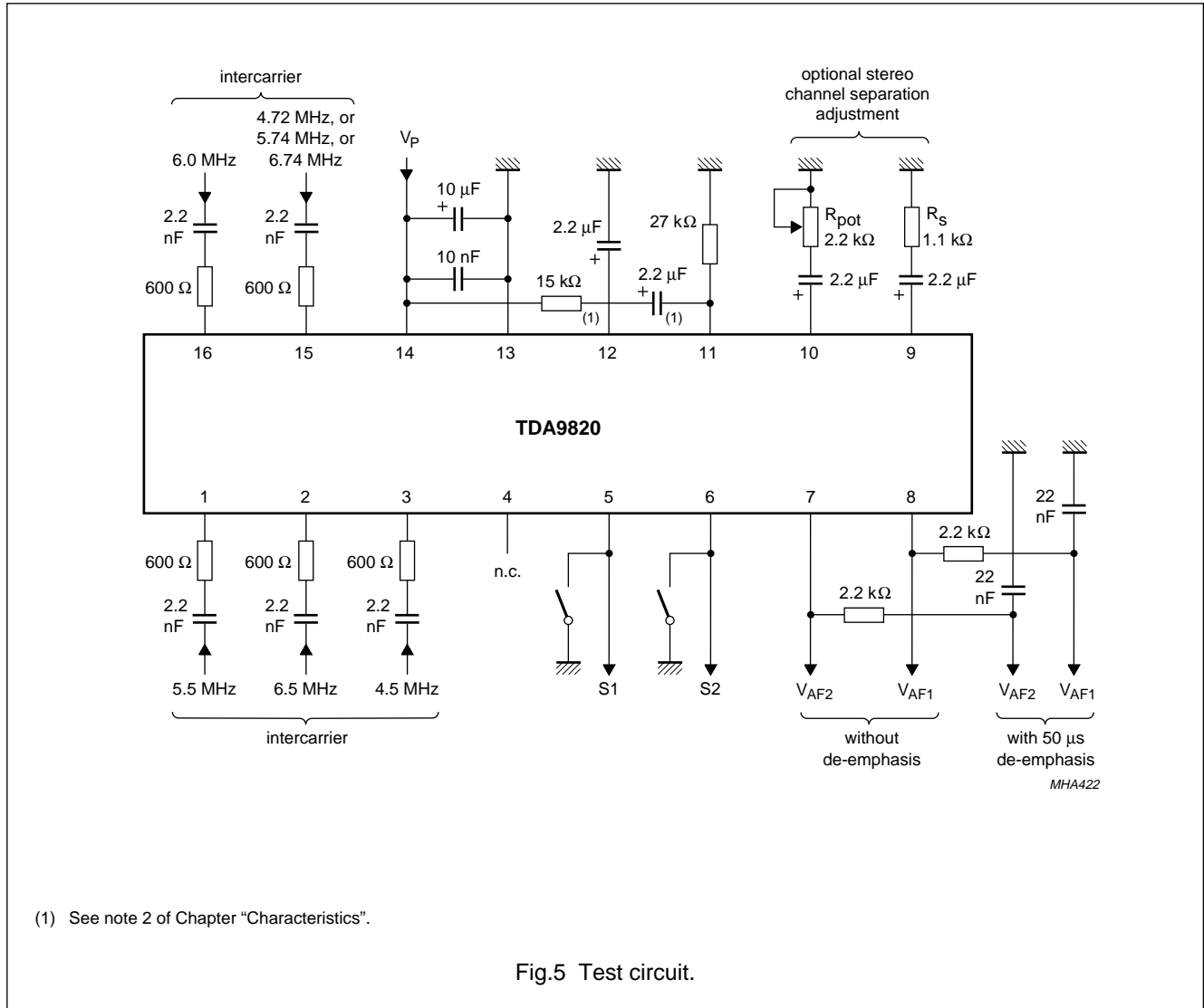


Fig.4 Internal circuitry.

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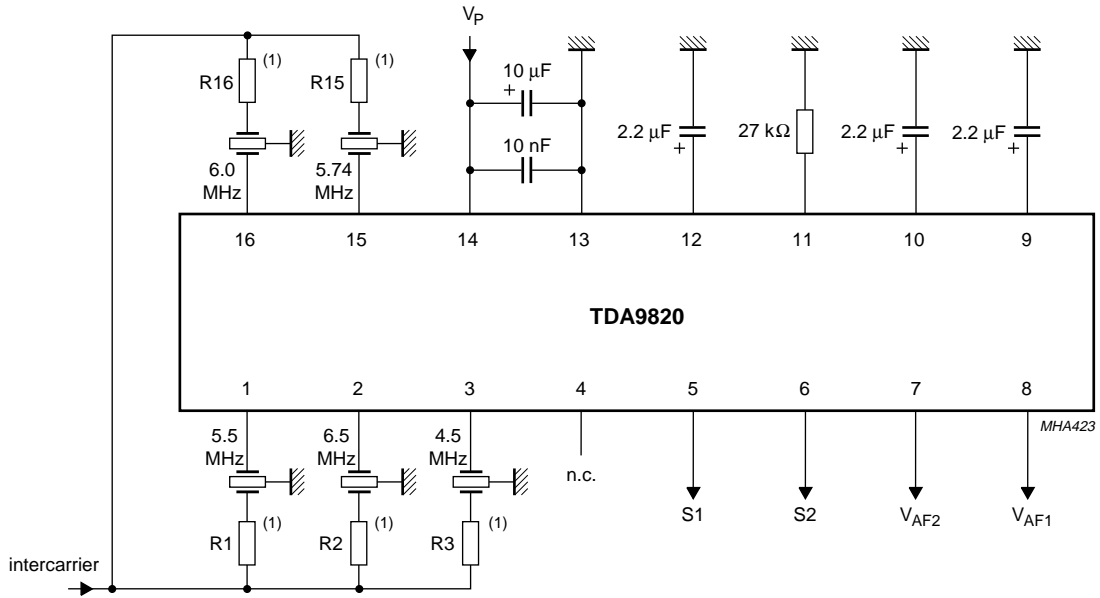
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TEST AND APPLICATION INFORMATION



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(1) Resistor value depends on filter.

Fig.6 Application circuit.

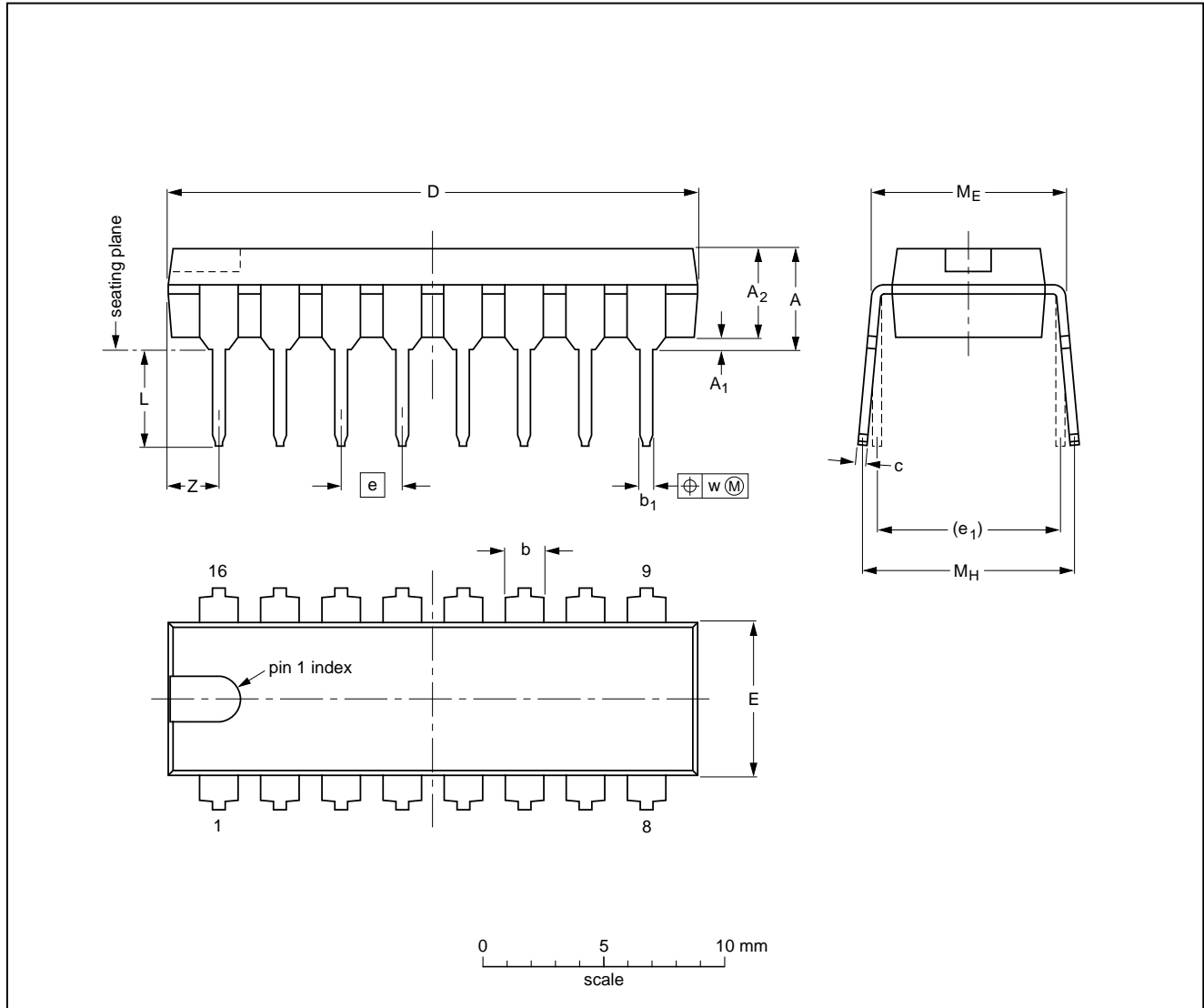
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PACKAGE OUTLINES

DIP16: plastic dual in-line package; 16 leads (300 mil); long body

SOT38-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.7	0.51	3.7	1.40 1.14	0.53 0.38	0.32 0.23	21.8 21.4	6.48 6.20	2.54	7.62	3.9 3.4	8.25 7.80	9.5 8.3	0.254	2.2
inches	0.19	0.020	0.15	0.055 0.045	0.021 0.015	0.013 0.009	0.86 0.84	0.26 0.24	0.10	0.30	0.15 0.13	0.32 0.31	0.37 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

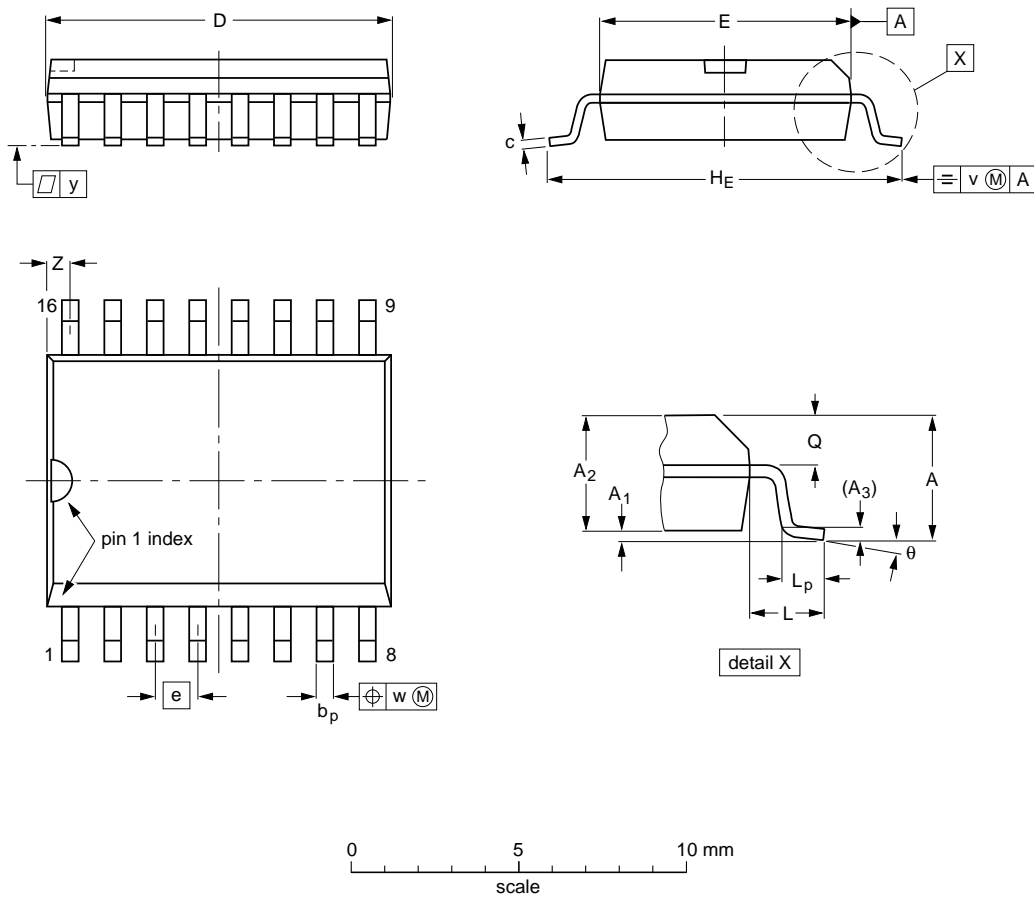
OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT38-1	050G09	MO-001AE				92-10-02 95-01-19

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SO16: plastic small outline package; 16 leads; body width 7.5 mm

SOT162-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	10.5 10.1	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8° 0°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.41 0.40	0.30 0.29	0.050	0.42 0.39	0.055	0.043 0.016	0.043 0.039	0.01	0.01	0.004	0.035 0.016	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT162-1	075E03	MS-013AA				92-11-17 95-01-24

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

DIP

SOLDERING BY DIPPING OR BY WAVE

The maximum permissible temperature of the solder is 260 °C; solder at this temperature must not be in contact with the joint for more than 5 seconds. The total contact time of successive solder waves must not exceed 5 seconds.

The device may be mounted up to the seating plane, but the temperature of the plastic body must not exceed the specified maximum storage temperature ($T_{stg\ max}$). If the printed-circuit board has been pre-heated, forced cooling may be necessary immediately after soldering to keep the temperature within the permissible limit.

REPAIRING SOLDERED JOINTS

Apply a low voltage soldering iron (less than 24 V) to the lead(s) of the package, below the seating plane or not more than 2 mm above it. If the temperature of the soldering iron bit is less than 300 °C it may remain in contact for up to 10 seconds. If the bit temperature is between 300 and 400 °C, contact may be up to 5 seconds.

SO

REFLOW SOLDERING

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at 45 °C.

WAVE SOLDERING

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

REPAIRING SOLDERED JOINTS

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

**Multistandard/dual channel TV FM
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TDA9820**DEFINITIONS**

Data sheet status	
Objective specification	This data sheet contains target or goal specifications for product development.
Preliminary specification	This data sheet contains preliminary data; supplementary data may be published later.
Product specification	This data sheet contains final product specifications.
Limiting values	
Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.	
Application information	
Where application information is given, it is advisory and does not form part of the specification.	

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

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NOTES

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NOTES

Philips Semiconductors – a worldwide company

Argentina: see South America

Australia: 34 Waterloo Road, NORTH RYDE, NSW 2113,
Tel. +61 2 9805 4455, Fax. +61 2 9805 4466

Austria: Computerstr. 6, A-1101 WIEN, P.O. Box 213,
Tel. +43 1 60 101, Fax. +43 1 60 101 1210

Belarus: Hotel Minsk Business Center, Bld. 3, r. 1211, Volodarski Str. 6,
220050 MINSK, Tel. +375 172 200 733, Fax. +375 172 200 773

Belgium: see The Netherlands

Brazil: see South America

Bulgaria: Philips Bulgaria Ltd., Energoproject, 15th floor,
51 James Bourchier Blvd., 1407 SOFIA,
Tel. +359 2 689 211, Fax. +359 2 689 102

Canada: PHILIPS SEMICONDUCTORS/COMPONENTS,
Tel. +1 800 234 7381

China/Hong Kong: 501 Hong Kong Industrial Technology Centre,
72 Tat Chee Avenue, Kowloon Tong, HONG KONG,
Tel. +852 2319 7888, Fax. +852 2319 7700

Colombia: see South America

Czech Republic: see Austria

Denmark: Prags Boulevard 80, PB 1919, DK-2300 COPENHAGEN S,
Tel. +45 32 88 2636, Fax. +45 31 57 1949

Finland: Sinikalliontie 3, FIN-02630 ESPOO,
Tel. +358 9 615800, Fax. +358 9 61580/xxx

France: 4 Rue du Port-aux-Vins, BP317, 92156 SURESNES Cedex,
Tel. +33 1 40 99 6161, Fax. +33 1 40 99 6427

Germany: Hammerbrookstraße 69, D-20097 HAMBURG,
Tel. +49 40 23 53 60, Fax. +49 40 23 536 300

Greece: No. 15, 25th March Street, GR 17778 TAVROS/ATHENS,
Tel. +30 1 4894 339/239, Fax. +30 1 4814 240

Hungary: see Austria

India: Philips INDIA Ltd, Shivsagar Estate, A Block, Dr. Annie Besant Rd.
Worli, MUMBAI 400 018, Tel. +91 22 4938 541, Fax. +91 22 4938 722

Indonesia: see Singapore

Ireland: Newstead, Clonskeagh, DUBLIN 14,
Tel. +353 1 7640 000, Fax. +353 1 7640 200

Israel: RAPAC Electronics, 7 Kehilat Saloniki St, TEL AVIV 61180,
Tel. +972 3 645 0444, Fax. +972 3 649 1007

Italy: PHILIPS SEMICONDUCTORS, Piazza IV Novembre 3,
20124 MILANO, Tel. +39 2 6752 2531, Fax. +39 2 6752 2557

Japan: Philips Bldg 13-37, Kohnan 2-chome, Minato-ku, TOKYO 108,
Tel. +81 3 3740 5130, Fax. +81 3 3740 5077

Korea: Philips House, 260-199 Itaewon-dong, Yongsan-ku, SEOUL,
Tel. +82 2 709 1412, Fax. +82 2 709 1415

Malaysia: No. 76 Jalan Universiti, 46200 PETALING JAYA, SELANGOR,
Tel. +60 3 750 5214, Fax. +60 3 757 4880

Mexico: 5900 Gateway East, Suite 200, EL PASO, TEXAS 79905,
Tel. +9-5 800 234 7381

Middle East: see Italy

Netherlands: Postbus 90050, 5600 PB EINDHOVEN, Bldg. VB,
Tel. +31 40 27 82785, Fax. +31 40 27 88399

New Zealand: 2 Wagener Place, C.P.O. Box 1041, AUCKLAND,
Tel. +64 9 849 4160, Fax. +64 9 849 7811

Norway: Box 1, Manglerud 0612, OSLO,
Tel. +47 22 74 8000, Fax. +47 22 74 8341

Philippines: Philips Semiconductors Philippines Inc.,
106 Valero St. Salcedo Village, P.O. Box 2108 MCC, MAKATI,
Metro MANILA, Tel. +63 2 816 6380, Fax. +63 2 817 3474

Poland: Ul. Lukiska 10, PL 04-123 WARSZAWA,
Tel. +48 22 612 2831, Fax. +48 22 612 2327

Portugal: see Spain

Romania: see Italy

Russia: Philips Russia, Ul. Usatcheva 35A, 119048 MOSCOW,
Tel. +7 095 247 9145, Fax. +7 095 247 9144

Singapore: Lorong 1, Toa Payoh, SINGAPORE 1231,
Tel. +65 350 2538, Fax. +65 251 6500

Slovakia: see Austria

Slovenia: see Italy

South Africa: S.A. PHILIPS Pty Ltd., 195-215 Main Road Martindale,
2092 JOHANNESBURG, P.O. Box 7430 Johannesburg 2000,
Tel. +27 11 470 5911, Fax. +27 11 470 5494

South America: Rua do Rocio 220, 5th floor, Suite 51,
04552-903 São Paulo, SÃO PAULO - SP, Brazil,
Tel. +55 11 821 2333, Fax. +55 11 829 1849

Spain: Balmes 22, 08007 BARCELONA,
Tel. +34 3 301 6312, Fax. +34 3 301 4107

Sweden: Kottbygatan 7, Akalla, S-16485 STOCKHOLM,
Tel. +46 8 632 2000, Fax. +46 8 632 2745

Switzerland: Allmendstrasse 140, CH-8027 ZÜRICH,
Tel. +41 1 488 2686, Fax. +41 1 481 7730

Taiwan: PHILIPS TAIWAN Ltd., 23-30F, 66,
Chung Hsiao West Road, Sec. 1, P.O. Box 22978,
TAIPEI 100, Tel. +886 2 382 4443, Fax. +886 2 382 4444

Thailand: PHILIPS ELECTRONICS (THAILAND) Ltd.,
209/2 Sanpavuth-Bangna Road Prakanong, BANGKOK 10260,
Tel. +66 2 745 4090, Fax. +66 2 398 0793

Turkey: Talatpasa Cad. No. 5, 80640 GÜLTEPE/ISTANBUL,
Tel. +90 212 279 2770, Fax. +90 212 282 6707

Ukraine: PHILIPS UKRAINE, 4 Patrice Lumumba str., Building B, Floor 7,
252042 KIEV, Tel. +380 44 264 2776, Fax. +380 44 268 0461

United Kingdom: Philips Semiconductors Ltd., 276 Bath Road, Hayes,
MIDDLESEX UB3 5BX, Tel. +44 181 730 5000, Fax. +44 181 754 8421

United States: 811 East Arques Avenue, SUNNYVALE, CA 94088-3409,
Tel. +1 800 234 7381

Uruguay: see South America

Vietnam: see Singapore

Yugoslavia: PHILIPS, Trg N. Pasica 5/v, 11000 BEOGRAD,
Tel. +381 11 625 344, Fax. +381 11 635 777

For all other countries apply to: Philips Semiconductors, Marketing & Sales Communications,
Building BE-p, P.O. Box 218, 5600 MD EINDHOVEN, The Netherlands, Fax. +31 40 27 24825

Internet: <http://www.semiconductors.philips.com>

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